

Replace the paragraph beginning at page 1, line 24, with:

A1
When a chip-to-chip loop such as shown in Fig. 9 is utilized, bonding pads 6 on semiconductor device 7 are connected to each other by means of first ball 2, the bonding wire 1, and stud bump (second ball) 9.

Replace the paragraph beginning at page 1, line 27, with:

A2
In the reverse loop or chip-to-chip technique, secondary bonding is performed on the bonding pad 6 on the chip. Here, a stud bump 9 is formed in advance on bonding pad 6 as shown in Fig. 10, and the secondary bonding is performed on stud bump 9, using a capillary 4 and a wire cut clamper 5 as shown in Fig. 11. Namely, an on-bump secondary bonding technique is used. In the on-bump secondary bonding technique, the step of arranging a stud bump is necessary, separate from the step of arranging the wire. This results in larger number of steps required for wire bonding, resulting in low efficiency in manufacturing the semiconductor devices.

Replace the paragraph beginning at page 5, line 27, with:

A3
Fig. 6 is a side view showing a characteristic step of manufacturing a semiconductor device in accordance with a second embodiment of the present invention.

Replace the paragraph beginning at page 6, line 4, with:

A4
Fig. 9 is a cross sectional view showing another example (chip-to-chip loop) of a conventional method of wire connection.